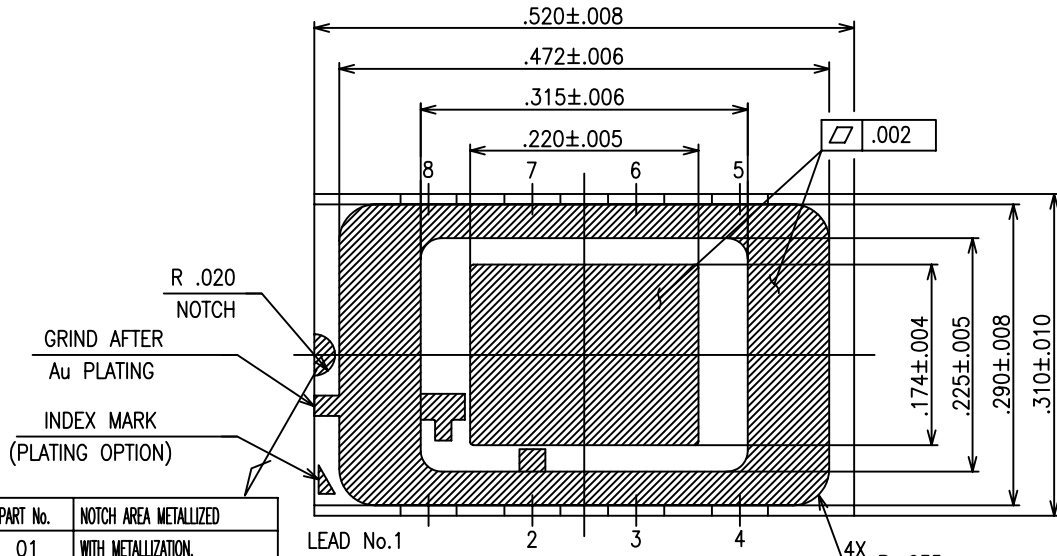
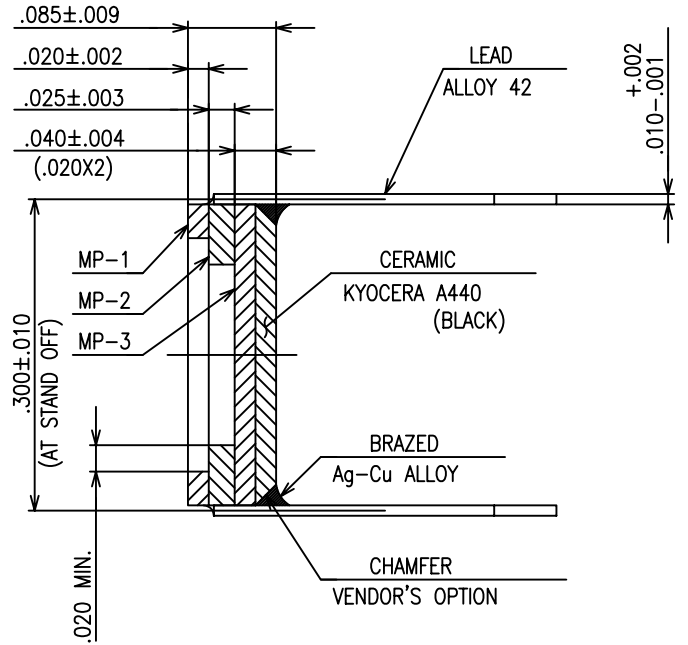


SSM P/N: CSB00820

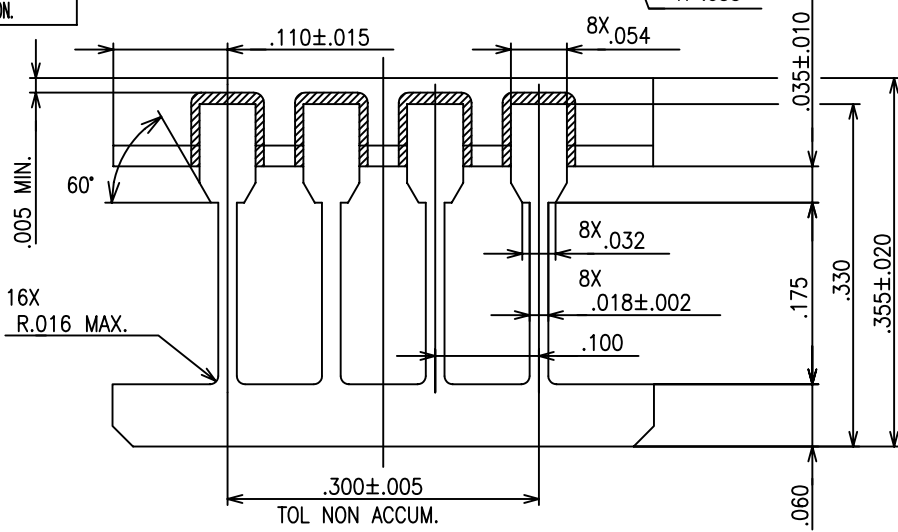


R .020 NOTCH
GRIND AFTER Au PLATING
INDEX MARK (PLATING OPTION)

PART No.	NOTCH AREA METALLIZED
01	WITH METALLIZATION.
02	WITHOUT METALLIZATION.



- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
 5. LEAD RESISTANCE : 0.20 OHM MAX.
 6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEAD.
 7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.



SBO08H047-2 S=0 D=0

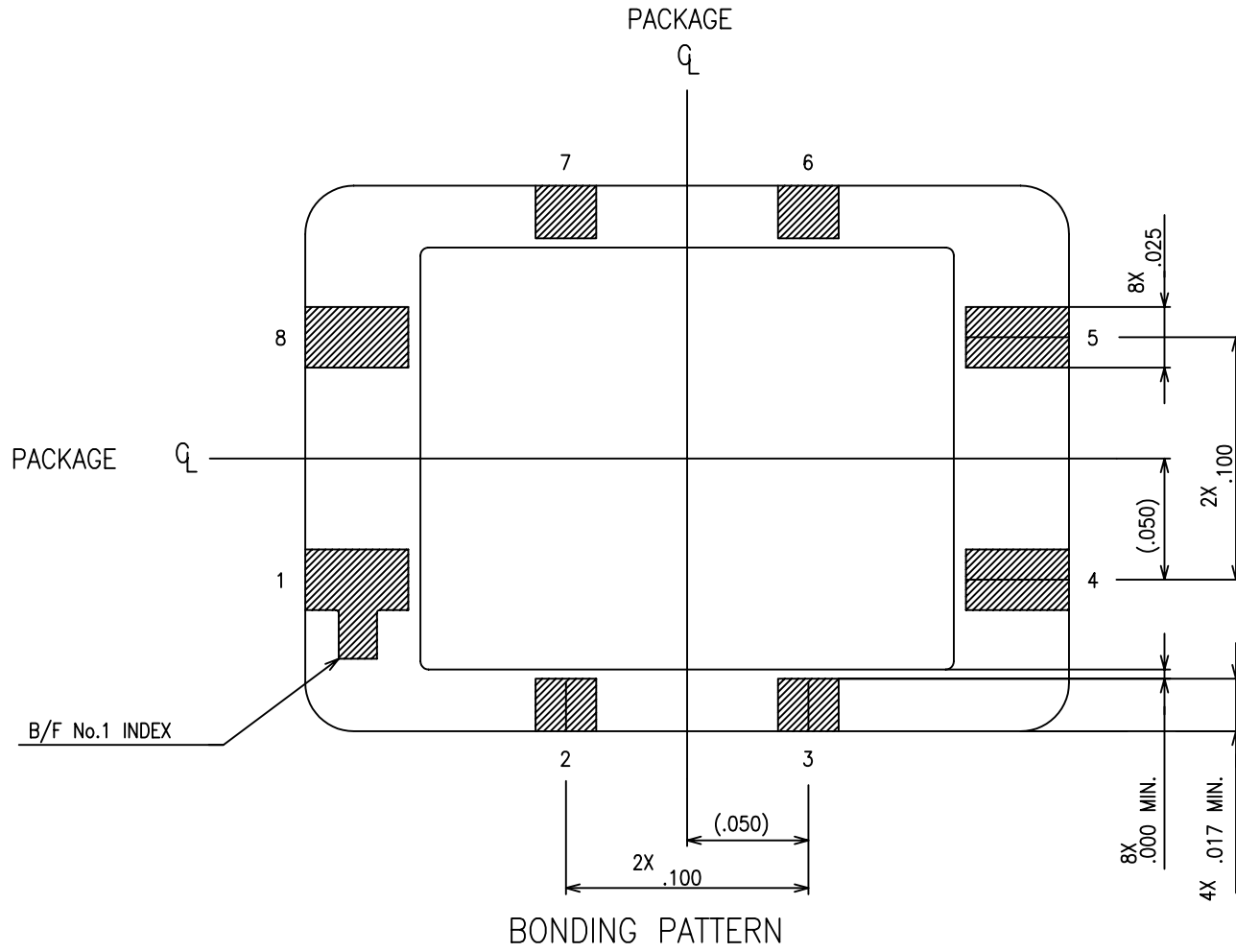
SBO08H047-1 S=0 D=0

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED
△G	ADDED : PART No.02 , NOTE 6,7,SHEET No.3,5~7 , CHANGED : SHEET No.2.	FEB.07	Y.H/Y.A	TO.H/MSJ	H.SA
△F	REDRAWN	MAR.06	S.SH	H.S/KI	T.A
△E	CONVERTED CAD DATA	MAY.20.03	S.SE	H.SU/SF	T.A
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME 8 LEAD SIDE BRAZED PACKAGE
TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION
SCALE 8 / 1 MATERIAL AS INDICATED
KYOCERA KYOCERA CORPORATION KYOTO JAPAN

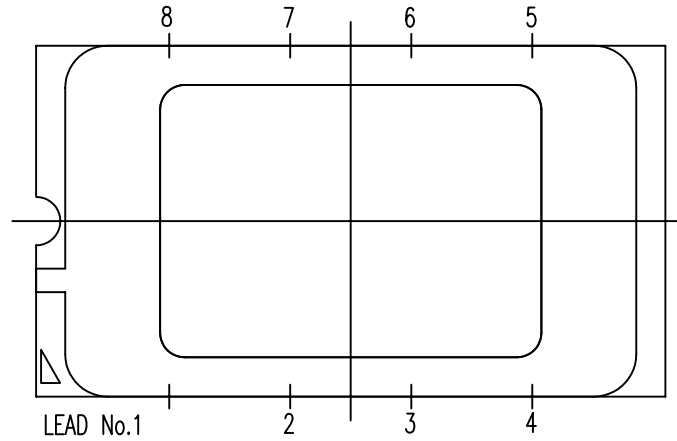
DRAWN	CHECKED	APPROVED	DATE
S.SE	H.SU/SF	T.A	MAR.97
DRAWING NO. KD-S77047-G			SHEET 1/7





MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
	△	REDRAWN	FEB.5.'07	Y.H/Y.A	TO.H/M.SU	8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.SE	H.SU/S.F	T.A	MAR.977
	△	REDRAWN	MAR.6.'96	S.SH	H.S/K.I	SCALE 20 / 1	MATERIAL				
	△	CONVERTED CAD DATA	MAY.20.'93	S.SE	H.SU/S.F						
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	THIRD ANGLE PROJECTION	DRAWING NO. KD-S77047-G			SHEET 2 / 7



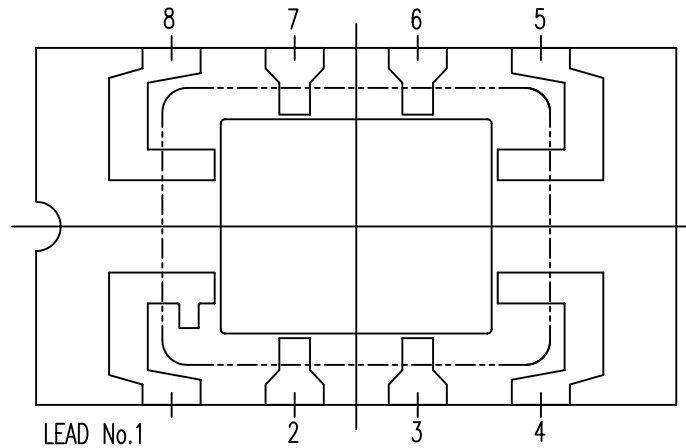


MP-1
 (PART 01,02)

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.SE	HSU/SF	T.A	NOV.11'82
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	△	ADDED : THIS SHEET	FEB.5'87	Y.H/Y.A	TO.H/MSU	H.SA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
		CHANGED	DATE	DRAWN	CHECKED	APPROVED		KD-S77047-G		3 / 7	

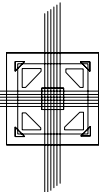


SSM P/M: CSB00820



MP-2
 (PART 01)

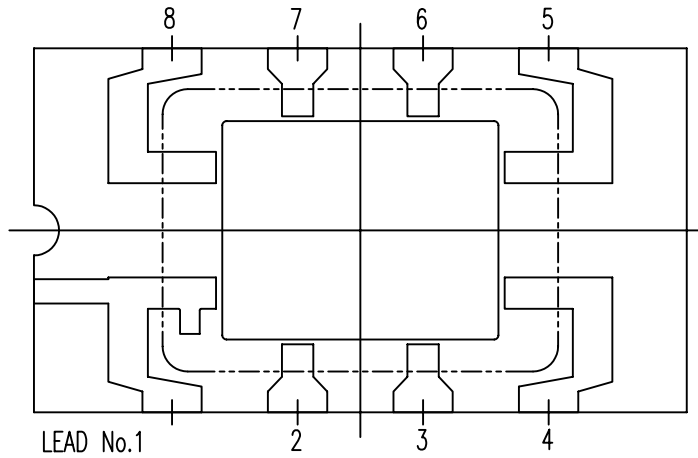
MODIFICATION						NAME 8 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
								S.SE	H.SU/SF	T.A	NOV.11'82
△	ADDED : PART No.	FEB.5'07	Y.H/YA	TO.H/MSU	H.SA	SCALE 10 / 1	MATERIAL				
△	REDRAWN	MAR.6'96	S.SH	H.S/KI	T.A						
△	CONVERTED CAD DATA	MAY.20'93	S.SE	H.SU/SF	T.A						
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S77047-G		SHEET 4 / 7	



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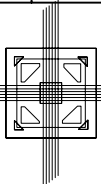
SSM P/N: CSB00820



MP-2

(PART 02)

MODIFICATION						NAME 8 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE 10 / 1	MATERIAL	/	/	/	/
	△	ADDED : THIS SHEET	FEB.5'07	Y.H/YA	TO.H/MSU	H.SA	THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S77047-G			SHEET 5 / 7

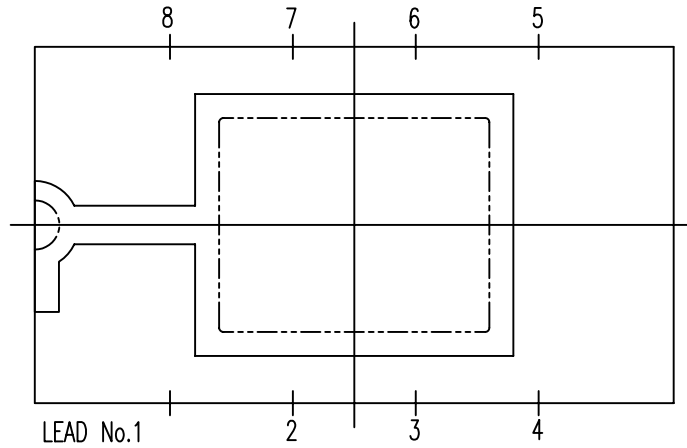


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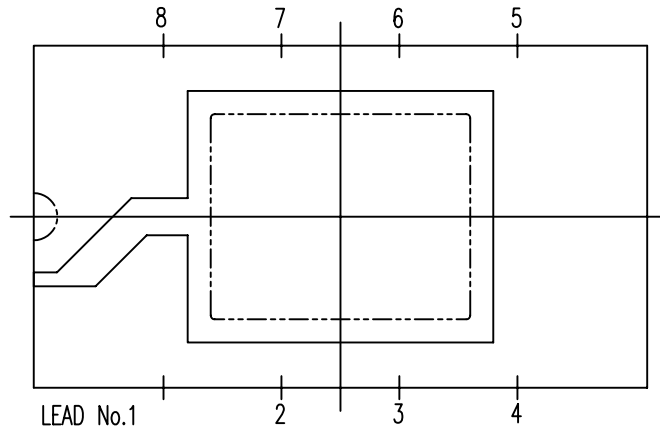


MP-3
(PART 01)


MODIFICATION						NAME 8 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.SE	CHECKED H.SU/SF	APPROVED T.A	DATE NOV.11'82
						SCALE 10 / 1	MATERIAL	/	/		
	△	ADDED : THIS SHEET	FEB.5'87	Y.H/Y.A	TO.H/MSJ	H.SA	THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S77047-G			SHEET 6 / 7



SSM P/N: CSB00820



MP-3
(PART 02)

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.SE	H.SU/SF	T.A	NOV.11'82
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	△ ADDED : THIS SHEET	FEB.87	Y.H/Y.A	TOH/MSU	H.SA	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KD-S77047-G			7 / 7	

